



Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model
[List multiple models if applicable.]

HP Spectre x360 Convertible PC 13

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm M/B, microsd Card D/B, Touch-Pad-PCB, Audio-D/B, IR board, touch board	6
Batteries	All types including standard alkaline and lithium coin or button style batteries Main Battery	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps 13"3	1
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		
External electrical cables and cords	Power cord	1
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		

Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Screwdriver	#1, #0/T5
Description #2	
Description #3	
Description #4	
Description #5	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove base screw *2,base rubber foot,screw *4 and base sub-assy
2. Remove battery screw *4 ,release battery connector and remove battery
3. Remove Mylar ,L/R fan housing screw *4 ,SSD Card screw *1 ,audio board screw *2
4. Release L/R fan connector,LVDS cable connector,Wlan connector*2,camera connector,IR board connector ,power DB connector
5. Take out L/R fan,SSD,Audio D/B
6. Remove L/R sperker screw *8 ,SD card board screw *1,TP screw *3,M/B screw *3
7. Release finger print connector,TP connector ,KB connector,KB light connector
8. Remove L/R speaker,TP,MB,SD card board and FFC *3 (Toughpad,SD card FFC,Power FFC)
9. Remove heat pipe ans screw *3
10. Remove Hinge screw *4 and LCD module assy

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.21 Total part



3.22 Remove Rear side rubber, base screw and base assy



3.23 Remove Mylar, SSD card, Thermal fan, Audio Board and battery, all screw.



3.24 Remove Touchpad, MB board, Thermal pipe, speaker, SD Board, SD Board FFC, Audio board FFC, Touchpad FFC and all screw.



3.25 The LCD module is not disassembly

